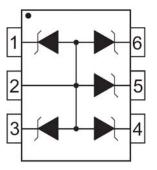




Feature

- 100W peak pulse power per line ($t_P = 8/20\mu S$)
- SC-70-6L package
- Protect 4 lines bidirectional and 5 lines unidirectional
- Monolithic structure
- Working voltage: 5V
- Low clamping voltage
- ESD protection > 25KV
- Low leakage current
- RoHS compliant
- Transient protection for data lines to IEC 61000-4-2(ESD) \pm 15KV(air),
 - \pm 8KV(contact); IEC 61000-4-4 (EFT) 40A (5/50ns)



Applications

- Cellular phones
- MP3 players
- Notebook
- PDAs
- Digital cameras
- Cellular phone base stations

Electrical characteristics per line@25°C(unless otherwise specified) note1

Parameter	ameter Symbol Conditions		Min.	Тур.	Max.	Units
Reverse stand-off voltage	V_{RWM}				5	V
Reverse Breakdown voltage	V_{BR}	$I_t = 1mA$	6			V
Reverse Leakage Current	I _R	V _{RWM} = 5V T=25°C			5	μA
Clamping Voltage	V _C	$I_{PP} = 1A$ $t_P = 8/20 \mu S$			8.8	V
Clamping Voltage	Vc	I _{PP} =10A t _P = 8/20μ S			10.0	V
Junction Capacitance	C _j	V _R =0V f = 1MHz		60		pF

Absolute maximum rating @25℃ note1

Rating	Symbol	Value	Units
Peak Pulse Power (t _p =8/20µs)	P _{pp}	100	Watts
Forward voltage@1A, 8/20µs	V _F	1.5	V
Operating Temperature	TJ	-55 to +150	${\mathbb C}$
Storage Temperature	T _{STG}	-55 to +150	°C

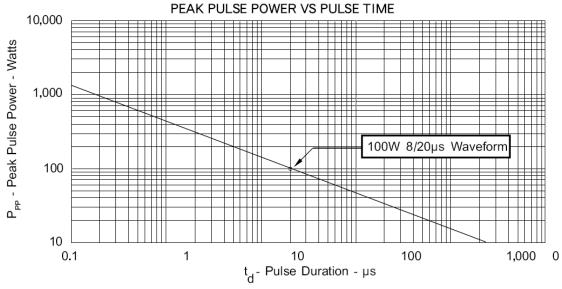
ESD Protector 1 <u>www.goodark.com</u>

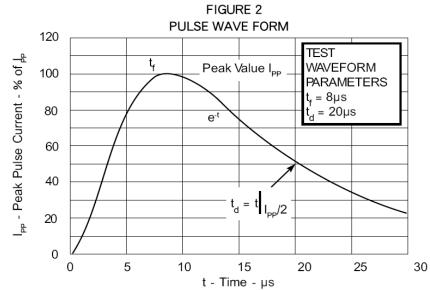


Note1: Pin 1, 3, 4, 5 or 6 to Pin 2

Typical Characteristics

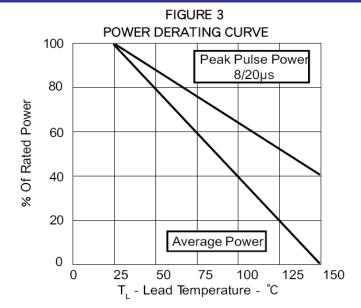




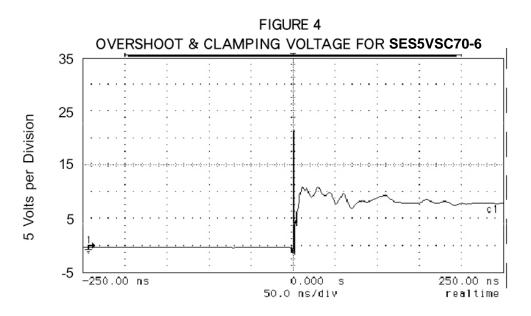




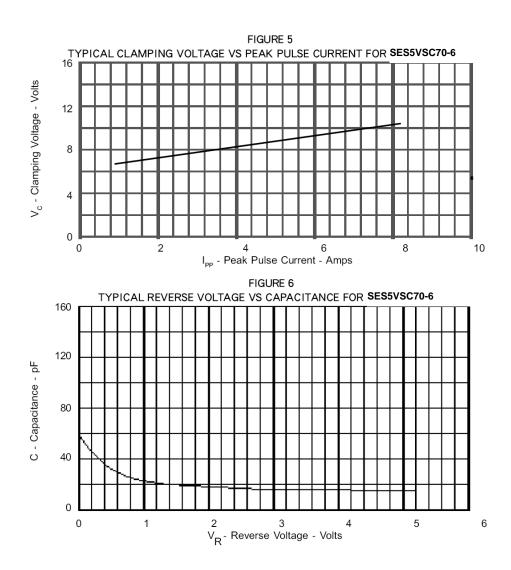
ESD Protector SES5VSC70-6 ROHS



Typical Characteristics



ESD Test Pulse: 5 kilovolt, 1/30ns (waveform)

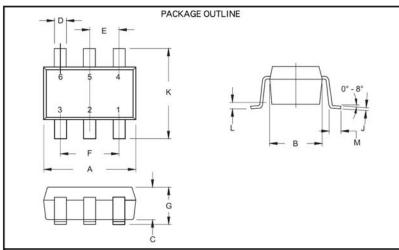








Product dimension and pad size

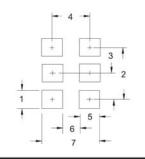




PACKAGE DIMENSIONS MILLIMETERS INCHES DIM MIN MAX MIN MAX 0.075 0.045 0.085 1.90 2.15 ABCDEFGJK 0.053 1.15 1.35 0.80 1.00 0.031 0.039 0.30 0.006 0.012 0.65 BSC 1.30 BSC 0.026 BSC 0.051 BSC 0.80 1.10 0.030 0.043 0.08 0.25 0.003 0.010 2.00 2.20 0.10 0.079 0.087 0.004 0 0.26 0.010

MOUNTING PAD

DIM	Millimeters	Inches
1	0.50	0.020
2	1.30	0.051
3	0.65	0.026
4	1.72	0.068
5	0.60	0.024
6	1.11	0.044
7	2.33	0.092



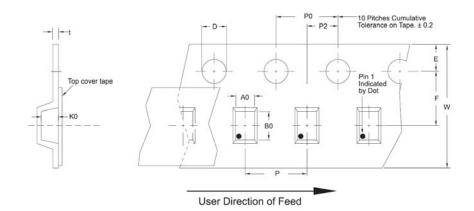
- Dimensioning and tolerances per ANSI Y14.5M, 1985.
 Controlling Dimension: Inches
 Dimensions are exclusive of mold flash and metal burs.

TAPE & REEL ORDERING NOMENCLATURE

- Surface mount product is taped and reeled in accordance with EIA-481,
 7 Inch Reel 3,000 pieces per 8mm tape.

Tape & Reel Specifications (Dimensions in millimeters)

Reel Dia.	Tape Width	A0	В0	K0	D	E	F	W	P0	P2	Р	tmax
178mm (7")	8mm	2.25 ± 0.10	2.34 ± 0.10	1.22 ± 0.10	1.50 ± 0.10	1.75 ± 0.10	3.50 ± 0.05	8.00 ±0.30	4.00 ±0.10	2.00 ±0.05	4.00 ±0.10	0.25





Application note

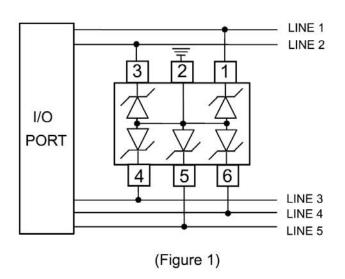
The sessvscro-6 Series is TVS arrays designed to protect I/O or data lines from the damaging effects of ESD or EFT. This product provides both unidirectional and bidirectional protection, with a surge capability of 100 Watts Ppp per line for an 8/20µs wave shape and ESD protection > 25 kilovolts.

COMMON-MODE UNIDIRECTIONAL CONFIGURATION (Figure 1)

The sessvscro-6 Series provides up to 5 lines of protection in a common-mode unidirectional configuration as depicted in Figure 1.

Circuit connectivity is as follows:

- · Line 1 is connected to Pin 1.
- · Line 2 is connected to Pin 3.
- · Line 3 is connected to Pin 4.
- Line 4 is connected to Pin 6.
- · Line 5 is connected to Pin 5.
- · Pin 2 is connected to ground.

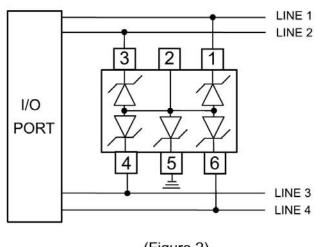


COMMON-MODE BIDIRECTIONAL CONFIGURATION (Figure 2)

The sessvsc70-6 Series provides up to 4 lines of protection in a common-mode bidirectional configuration as depicted in Figure 2.

Circuit connectivity is as follows:

- · Line 1 is connected to Pin 1.
- Line 2 is connected to Pin 3.
- · Line 3 is connected to Pin 4.
- · Line 4 is connected to Pin 6.
- · Pin 2 is not connected.
- Pin 5 is connected to ground.



(Figure 2)

ROHS 💝

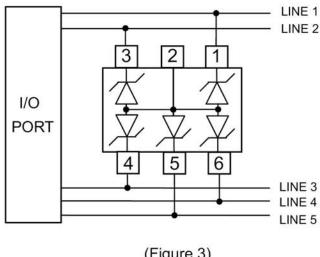
Application note

DIFFERENTIAL-MODE BIDIRECTIONAL CONFIGURATION (Figure 3)

The sessvsc70-6 Series provides up to 5 lines of protection in a differential-mode bidirectional configuration as depicted in Figure 3.

Circuit connectivity is as follows:

- · Line 1 is connected to Pin 1.
- · Line 2 is connected to Pin 3.
- Line 3 is connected to Pin 4.
- · Line 4 is connected to Pin 6.
- Line 5 is connected to Pin 5.
- · Pin 2 is not connected.



(Figure 3)

Circuit board layout and protection device placement:

Circuit board layout is critical for the suppression of ESD transients.

The following guidelines are recommended:

- Place the protection device as close to the input terminal or connector as possible. 1.
- 2. The path length between the protection device and the protected line should be minimized.
- 3. Keep parallel signal paths to a minimum.
- 4. Avoid running protection conductors in parallel with unprotected conductor.
- 5. Minimize all printed-circuit board conductive loops including power and ground loops.
- Minimize the length of the transient return path to ground.
- 7. Avoid using shared transient return paths to a common ground point.
- Ground planes should be used whenever possible. For multilayer printed-circuit boards, use ground vias.



Revision History

SES Series ESD Protector ROHS 🤝

SES5VSC70-6

Revision	Date	Changes
1.0	2008-7-3	-